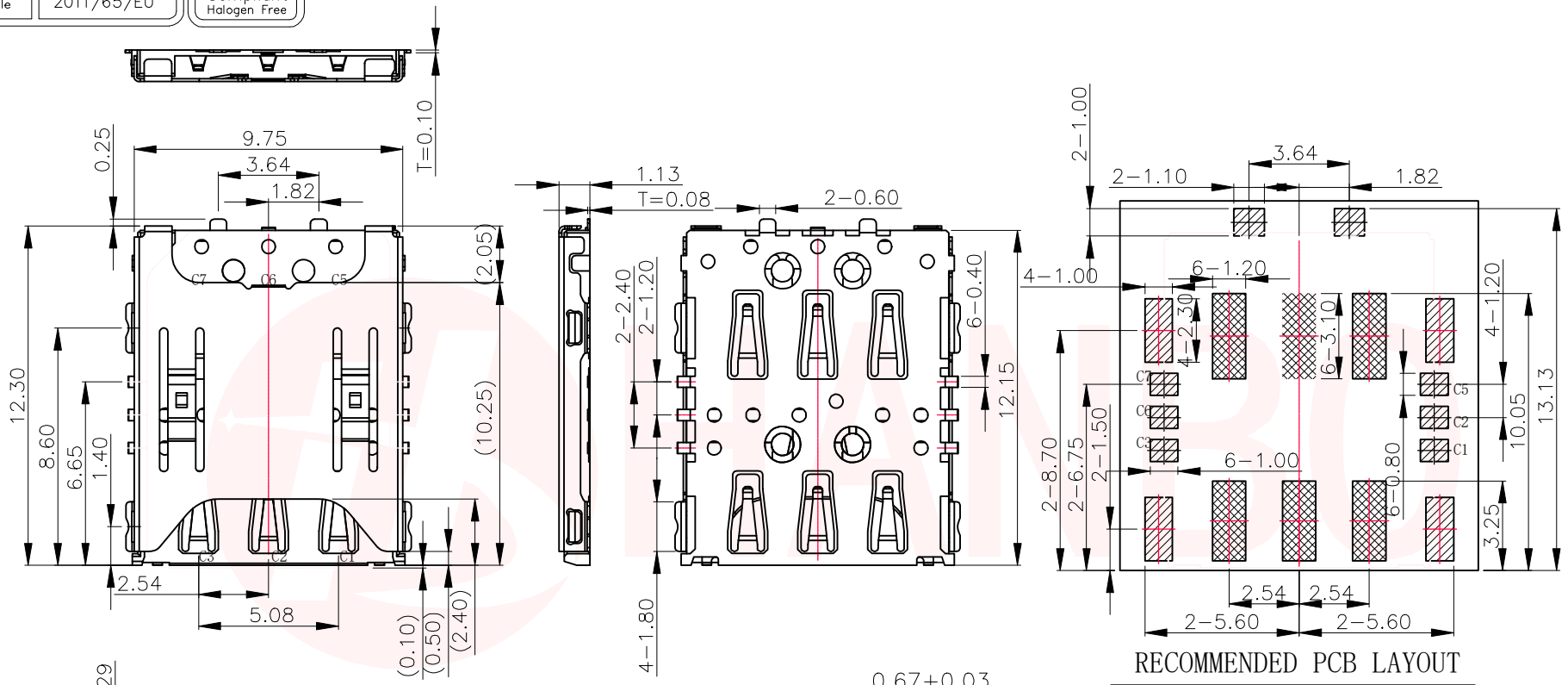




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



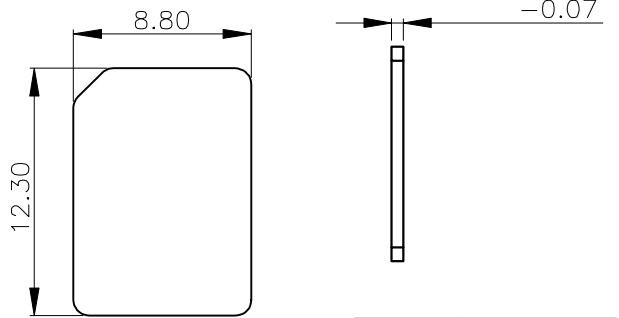
RECOMMENDED PCB LAYOUT

TOLERANCE: ± 0.05

- SMT SOLDER AREA
- COPPER RESTRICTED AREA
 - 1. TOUCH AREA OF CONTACT
 - TIPS NO ELECTRICAL FUNCTION
 - 2. NO FIRST PCB LAYOUT
 - CIRCUITS IN THE AREA

NOTES:

- MATERIAL:**
HOUSING: High Temperature Thermoplastic
Terminal: Copper Alloy
Shell: Stainless Steel
- PLATING:**
Terminal: 30u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA
100u" TIN PLATED ON SOLDER AREA
Shell: 50u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA
- TECHNICAL SPECIALITY:**
RATED VOLTAGE: 30V AC MAX.
CURRENT RATING: 0.5A MAX.
INSULATION RESISTANCE: 1000MΩ MIN
CONTACT RESISTANCE: 100mΩ MAX
WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES
OPERATING TEMPERATURE: -20℃ ~ +85℃ Humidity 80% R. HMAX



PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X : ±0.30 X.X : ±0.20 X.XX : ±0.10

ANGLES: X : ±2° X.X : ±1°

东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

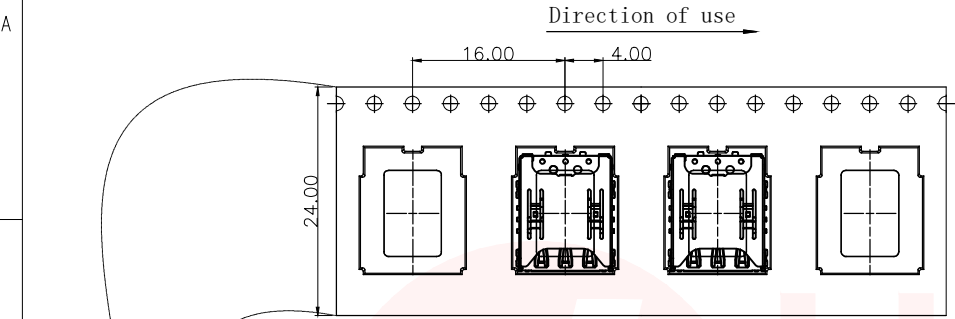
TITLE 1.13H NO-PUSH NANO SIM CARD

DWN	xiong	PART NO.	SNO-1430
CHKD	lee	SCALE: 1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET: 10F 1

CUSTOMER COPY

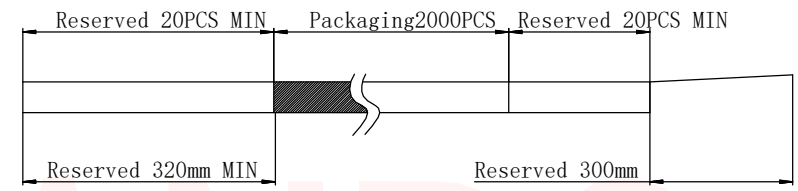


REV.	ECN NO OR DESCRIPTION	REVISED	DATE

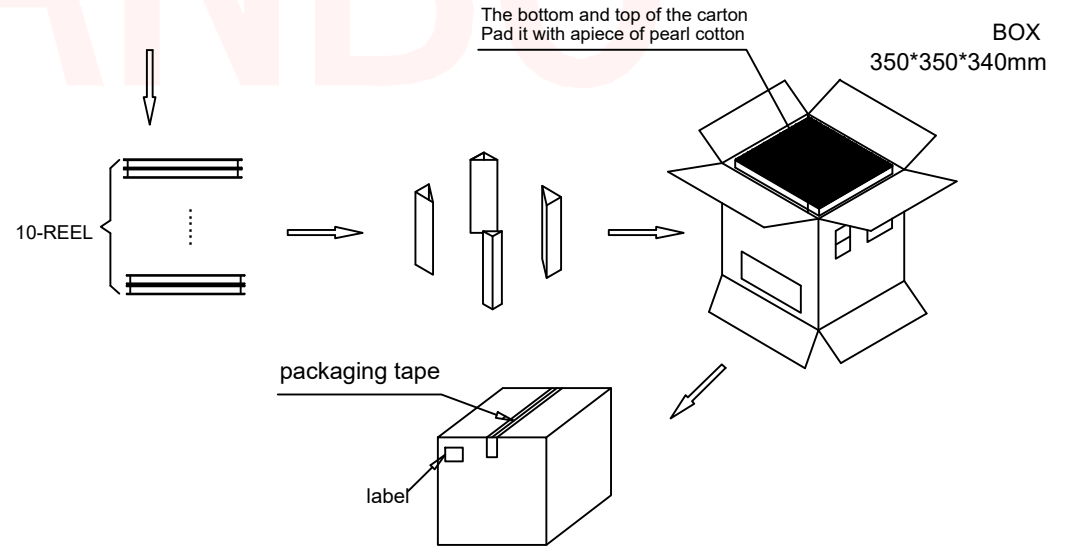
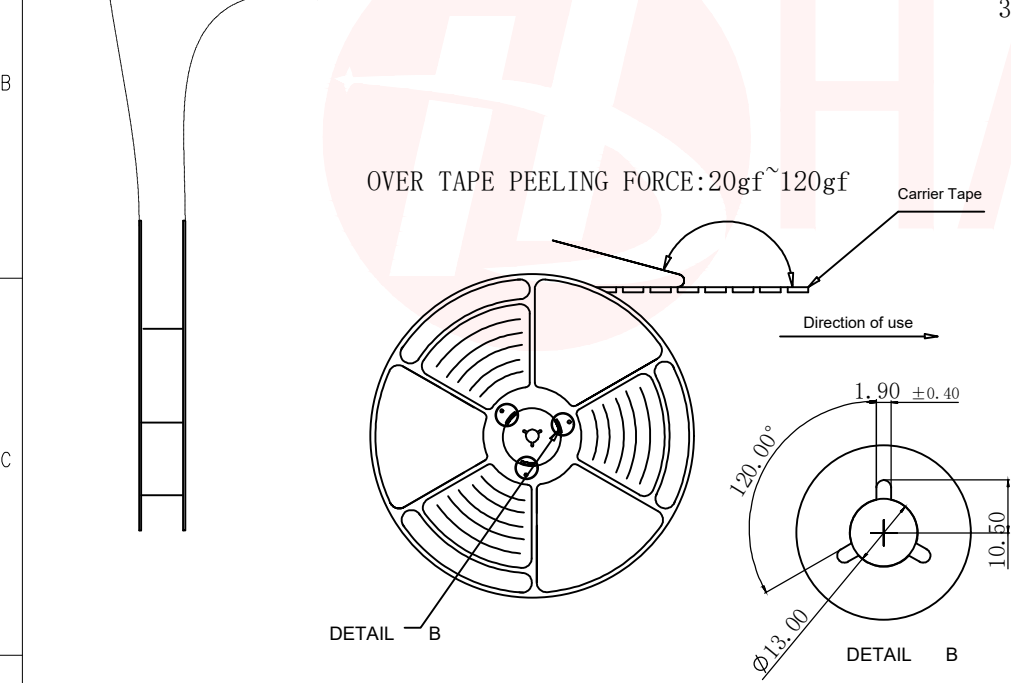


NOTES:

- 1、Packing quantity per plate: 2000PCS/Plate
- 2、Loading and packing method



- 3、Total packaging: 20000PCS/Box



Description	Quantity
Carrierband (Lucent, PET W=24 PH=16,T=0.3)	326.4m
Box (K=K,T=7.0,350*350*340)	1PCS
PE Bag (T=0.08mm, 730*760*730)	1PCS
Self-adhesive (W=21.30)	329.4m
Beam (K=K, T=7.0,95*95*290)	4PCS
Pearl Wool (340*340*18)	2PCS
REEL (BLUE, 13Inches*24mm, φ330)	10PCS
1.13H No-Push Nano-SIM Card	20000PCS

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	1.13H NO-PUSH NANO SIM CARD		
X :±0.30	X :±2°	DWN	xiong	PART NO. SNO-1430	
X.X :±0.20	X.X :±1°	CHKD	lee	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4	SHEET:10F 1
CUSTOMER COPY					